

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC377

Octal D-type Flip-Flops (with Enable)



ADE-205-501 (Z)
1st. Edition
Sep. 2000

Description

Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if the enable input $\overline{G}$ is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at the $\overline{G}$ input.

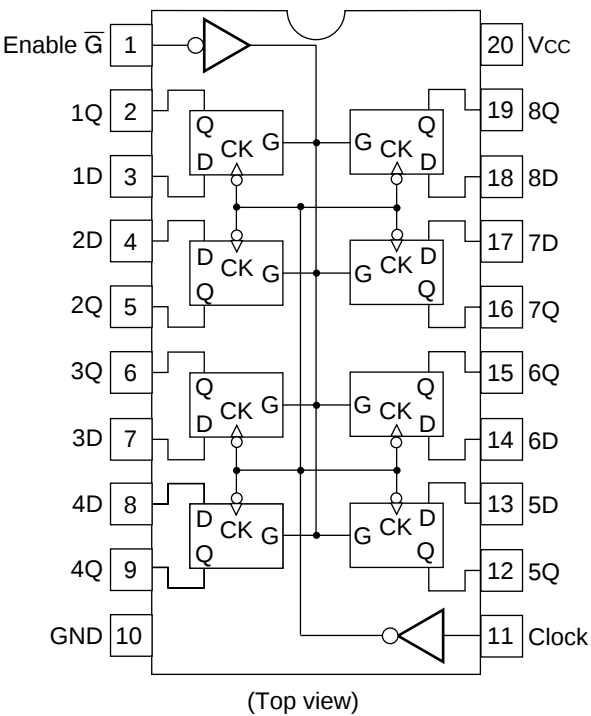
Features

- High Speed Operation: $t_{pd} = 13 \text{ ns typ (} C_L = 50 \text{ pF)}$
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2 \text{ to } 6 \text{ V}$
- Low Input Current: $1 \mu\text{A max}$
- Low Quiescent Supply Current: $I_{CC} \text{ (static)} = 4 \mu\text{A max (} T_a = 25^\circ\text{C)}$

Function Table

Inputs			Outputs	
Enable $\overline{G}$	Clock	Data	Q	$\overline{Q}$
H	X	X	Q_0	$\overline{Q}_0$
L		H	H	L
L		L	L	H
X	L	X	Q_0	$\overline{Q}_0$

Pin Arrangement



DC Characteristics

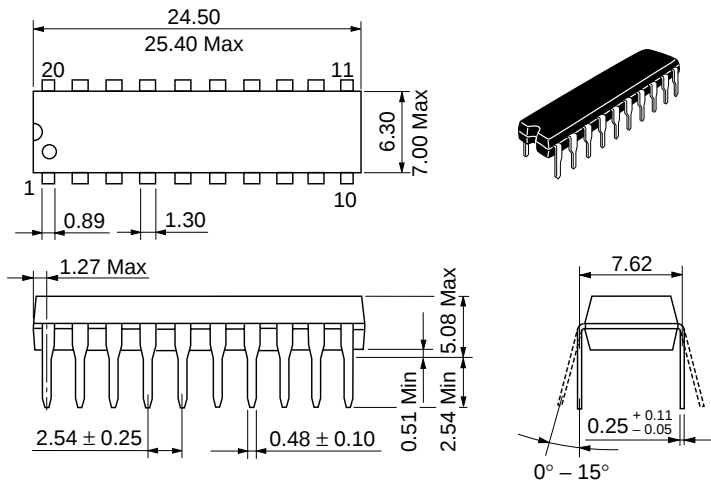
Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -4 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -5.2 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 5.2 mA
Off-state output current	I _{OZ}	6.0	—	—	±0.5	—	±5.0	μA	Vin = V _{IH} or V _{IL} , Vout = V _{CC} or GND	
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, Iout = 0 μA	

AC Characteristics (C_L = 50 pF, Input t_r = t_f = 6 ns)

Item	Symbol	V _{CC} (V)	Ta = −40 to						Unit	Test Conditions
			Ta = 25°C			+85°C				
			Min	Typ	Max	Min	Max			
Maximum clock frequency	f _{max}	2.0	—	—	6	—	5	MHz		
		4.5	—	—	30	—	24			
		6.0	—	—	35	—	28			
Propagation delay time	t _{PLH} t _{PHL}	2.0	—	—	140	—	175	ns		
		4.5	—	13	28	—	35			
		6.0	—	—	24	—	30			
Setup time	t _{su}	2.0	100	—	—	125	—	ns		
		4.5	20	5	—	25	—			
		6.0	17	—	—	21	—			
Hold time	t _h	2.0	5	—	—	5	—	ns		
		4.5	5	0	—	5	—			
		6.0	5	—	—	5	—			
Pulse width	t _w	2.0	80	—	—	100	—	ns		
		4.5	16	—	—	20	—			
		6.0	14	—	—	17	—			
Output rise/fall time	t _{TLH} t _{THL}	2.0	—	—	75	—	95	ns		
		4.5	—	5	15	—	19			
		6.0	—	—	13	—	16			
Input capacitance	C _{in}	—	—	5	10	—	10	pF		

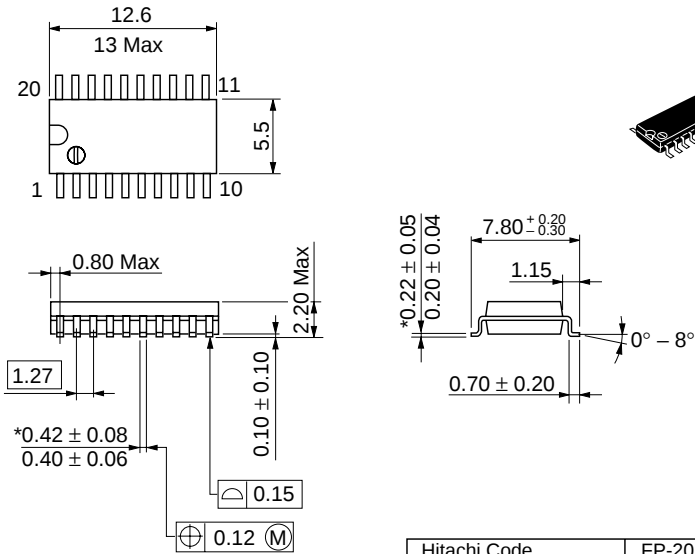
Package Dimensions

Unit: mm



Hitachi Code	DP-20N
JEDEC	—
EIAJ	Conforms
Mass (reference value)	1.26 g

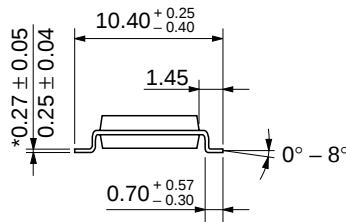
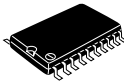
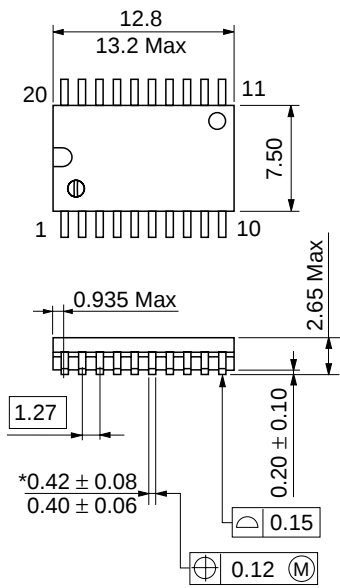
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-20DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.31 g

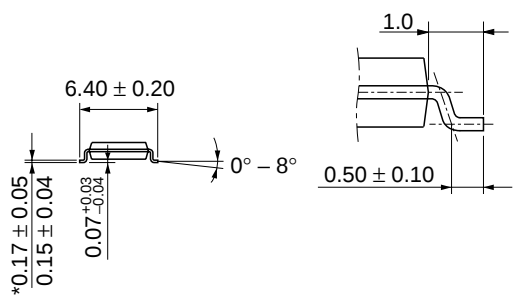
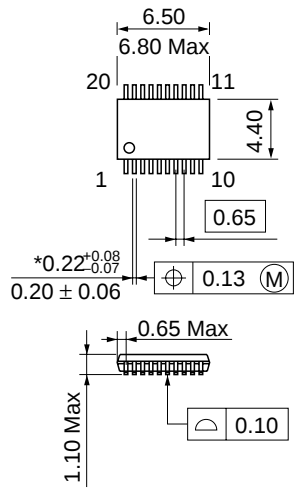
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-20DB
JEDEC	Conforms
EIAJ	—
Mass (reference value)	0.52 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-20DA
JEDEC	—
EIAJ	—
Mass (reference value)	0.07 g

Cautions

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